

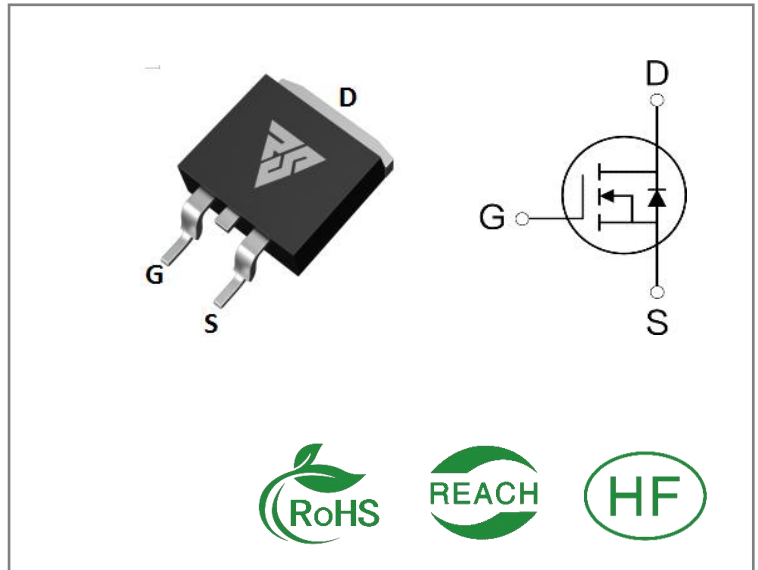
ID	R <sub>DS(ON)</sub> (Typ)	VDSS
13A	0.39Ω	500V

**Applications:**

- Switch Mode Power Supply(SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)

**Features:**

- Fast switching speed
- 100% avalanche tested
- Improved dv/dt capability


**Ordering Information**

Part Number	Package	Marking	Packing	Qty.
RS13N50S	T0-263	RS13N50S	Tape&reel	800 PCS

**Absolute Maximum Ratings** Tc= 25°C unless otherwise specified

Symbol	Parameter	RS13N50S	Units
VDSS	Drain-to-Source Voltage	500	V
ID	Continuous Drain Current TC=25°C	13	A
IDM	Pulsed Drain Current (Note*1)	52	
PD	Power Dissipation	130	W
VGS	Gate- to- Source Voltage	±30	V
EAS	Single Pulse Avalanche Energy L = 10mH,,VDD = 50V, RG = 25Ω	302	mJ
TL TPKG	Maximum Temperature for Soldering	300 260	°C
	Leads at 0.063in(1.6mm)from Case for 10 seconds Package Body for 10 seconds		
TJ and TSTG	Operating Junction and Storage Temperature Range	-55 to 150	

\* Drain Current Limited by Maximum Junction Temperature

Caution: Stresses greater than those listed in the“ Absolute Maximum Ratings” Table may cause permanent damage to the device.

**Thermal Resistance**

Symbol	Parameter	RS13N50S	Units	Test Conditions
R $\theta$ JC	Junction-to-Case	0.83	°C / W	Drain lead soldered to water cooled heatsink, PD adjusted for a peak junction temperature of + 1 5 0 °C
R $\theta$ JA	Junction-to-Ambient	62.5		1 cubic foot chamber, free air.

**OFF Characteristics** T<sub>J</sub>= 25°C unless otherwise specified

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
BVDSS	Drain- to- source Breakdown Voltage	500	--	--	V	VGS=0V, ID=250μA
IDSS	Drain- to- Source Leakage Current	--	--	1	μA	VDS=500V, VGS=0V
IGSS	Gate- to- Source Forward Leakage	--	--	100	nA	VGS=30V , VDS=0V
	Gate- to- Source Reverse Leakage	--	--	-100		VGS=-30V , VDS=0V

**ON Characteristics** T<sub>J</sub>=25°C unless otherwise specified

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
RDS(on)	Static Drain- to- Source On-Resistance(Note*2)	--	0.39	0.46	Ω	VGS=10V, ID=6.5A
VGS(TH)	Gate Threshold Voltage	3	--	4	V	VGS=VDS, ID=250μA

**Resistive Switching Characteristics** Essentially independent of operating temperature

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
td(ON)	Turn- on Delay Time	--	38	--	nS	VDS=250V ID=13A RG=25Ω
trise	Rise Time	--	7	--		
td(OFF)	Turn- OFF Delay Time	--	68	--		
tfall	Fall Time	--	30	--		

**Dynamic Characteristics** Essentially independent of operating temperature

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
Ciss	Input Capacitance	--	1215	--	pF	VGS=0V VDS=25V f=200KHz
Coss	Output Capacitance	--	116	--		
Crss	Reverse Transfer Capacitance	--	24	--		
Qg	Total Gate Charge	--	48	--	nC	VDS=400V ID=13A VGS=10V
Qgs	Gate- to- Source Charge	--	7	--		
Qgd	Gate-to-Drain(" Miller") Charge	--	28	--		

**Source- Drain Diode Characteristics**

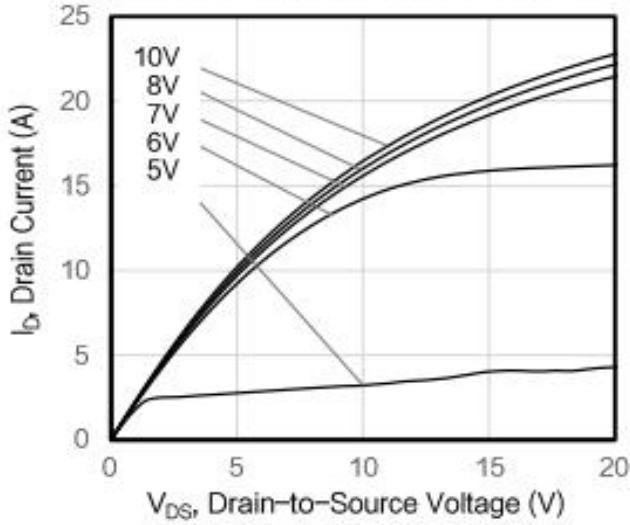
Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
IS	Continuous Source Current	--	--	13	A	Integral pn- diode in MOSFET
ISM	Maximum Pulsed Current	--	--	52	A	
VSD	Diode Forward Voltage	--	--	1.4	V	IS=6.5A,VGS=0V
trr	Reverse Recovery Time	--	320	--	nS	VGS=0V IS=13A,di/dt=100 A/μs
Qrr	Reverse Recovery Charge	--	3.85	--	μC	

**Notes:**

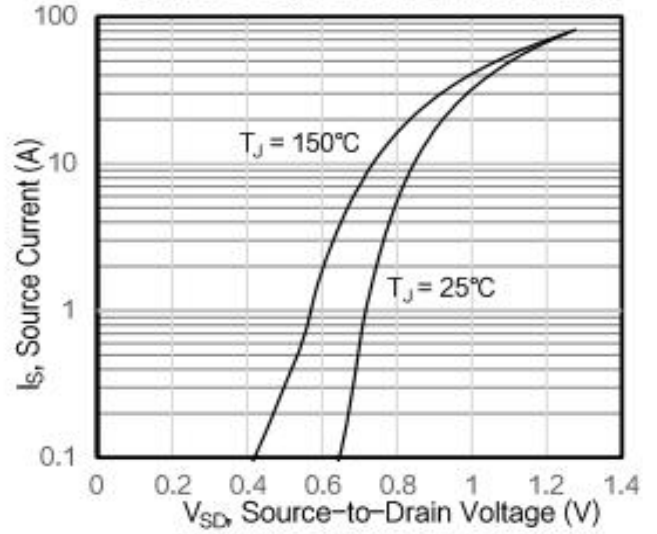
- \* 1. Repetitive rating, pulse width limited by maximum junction temperature.
- \* 2. Pulse Test: Pulse width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 1\%$

**Typical Feature Curve**

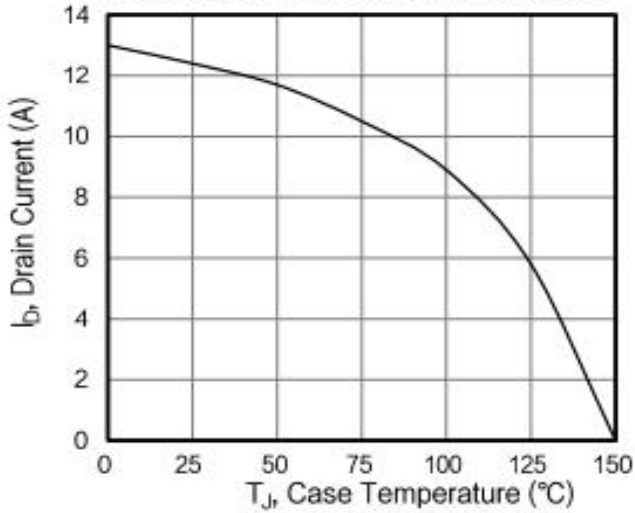
**Figure 1. Output Characteristics ( $T_J = 25^\circ\text{C}$ )**



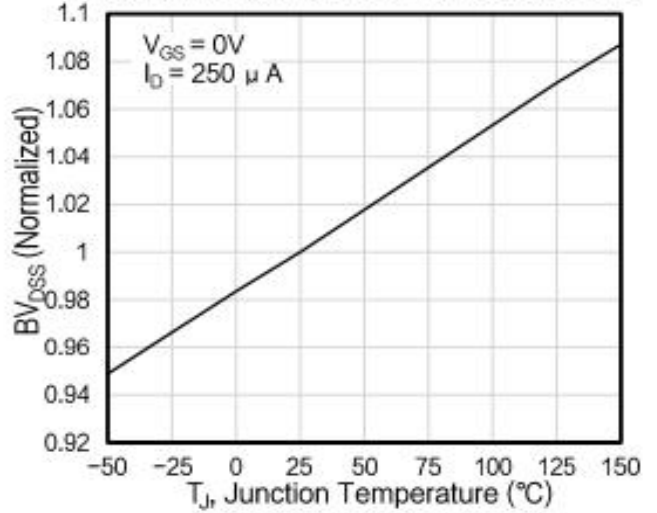
**Figure 2. Body Diode Forward Voltage**



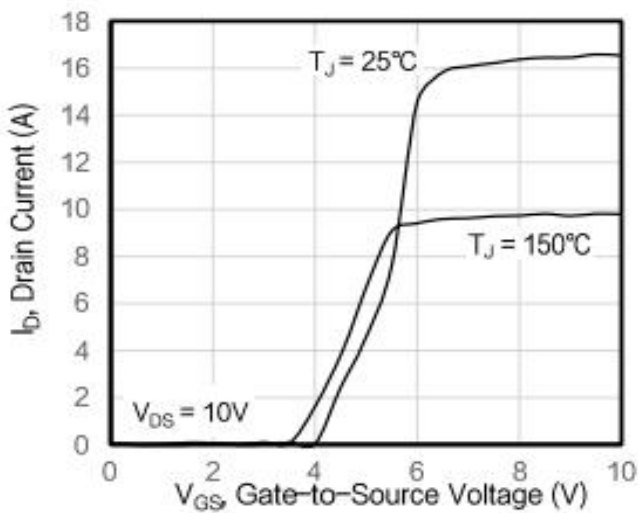
**Figure 3. Drain Current vs. Temperature**



**Figure 4.  $BV_{DSS}$  Variation vs. Temperature**



**Figure 5. Transfer Characteristics**



**Figure 6. On-Resistance vs. Temperature**

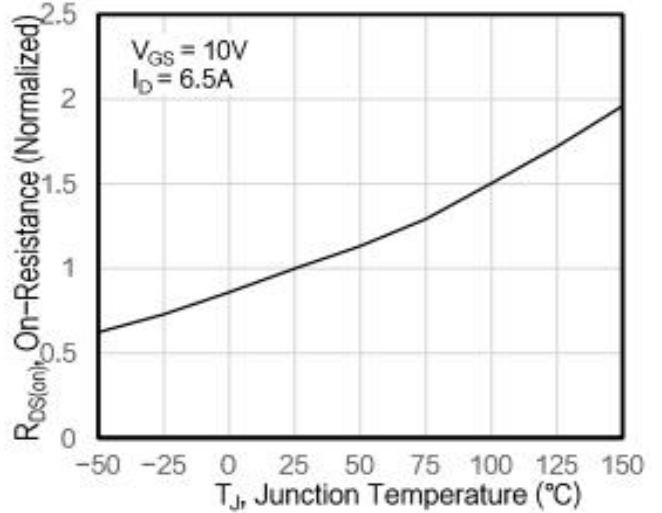


Figure 7. Capacitance

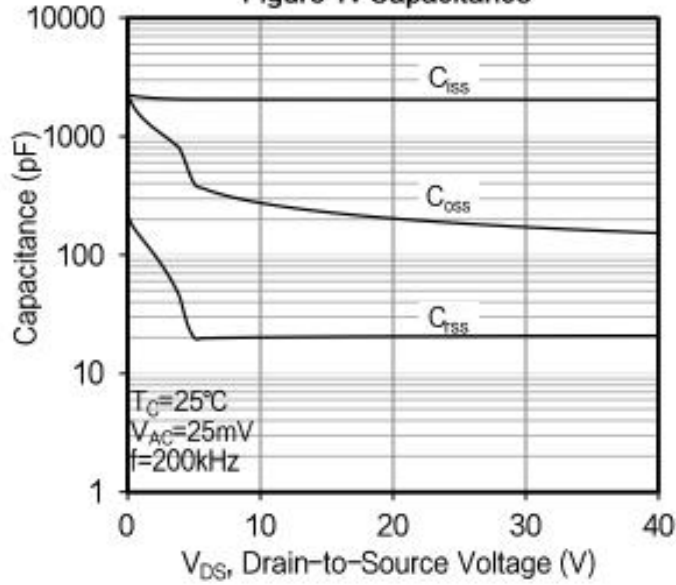


Figure 8. Gate Charge

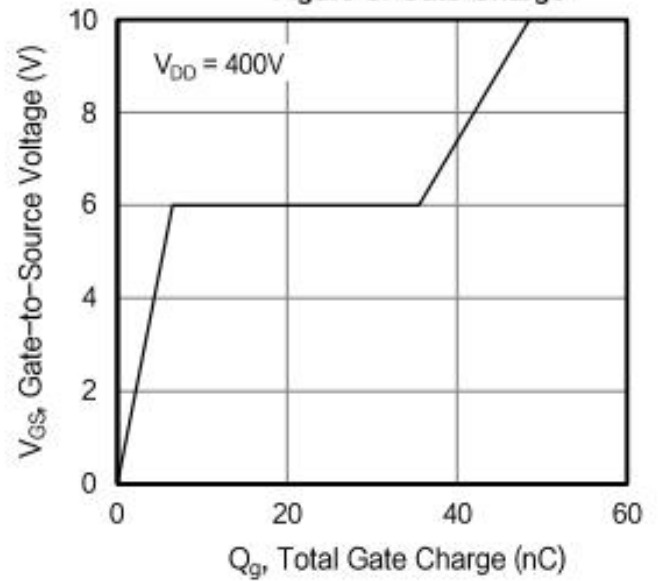
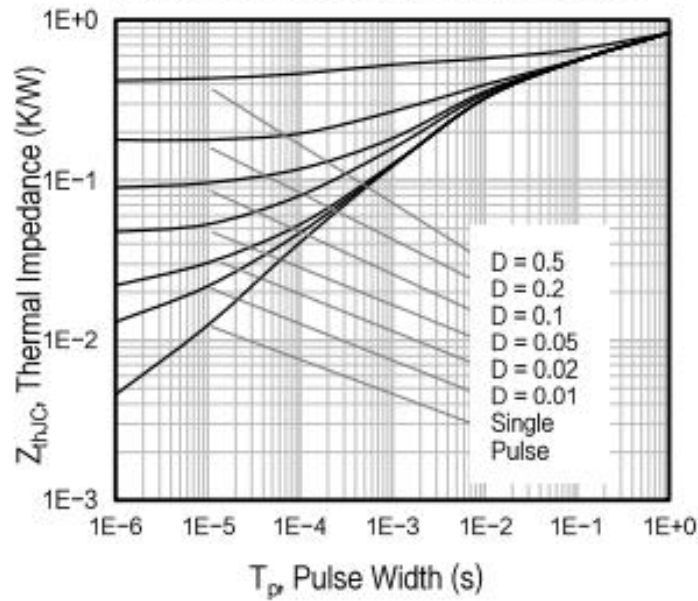
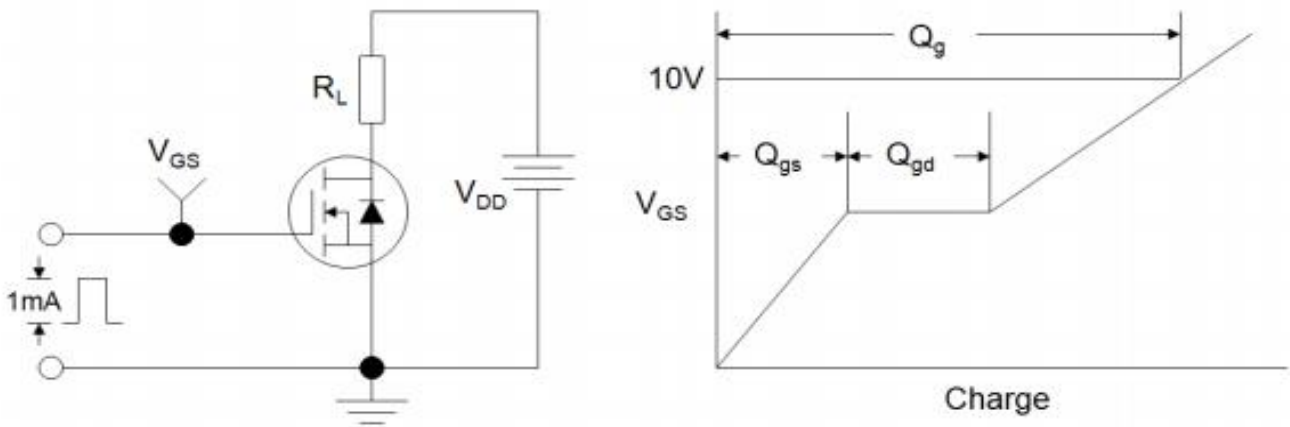


Figure 9. Transient Thermal Impedance

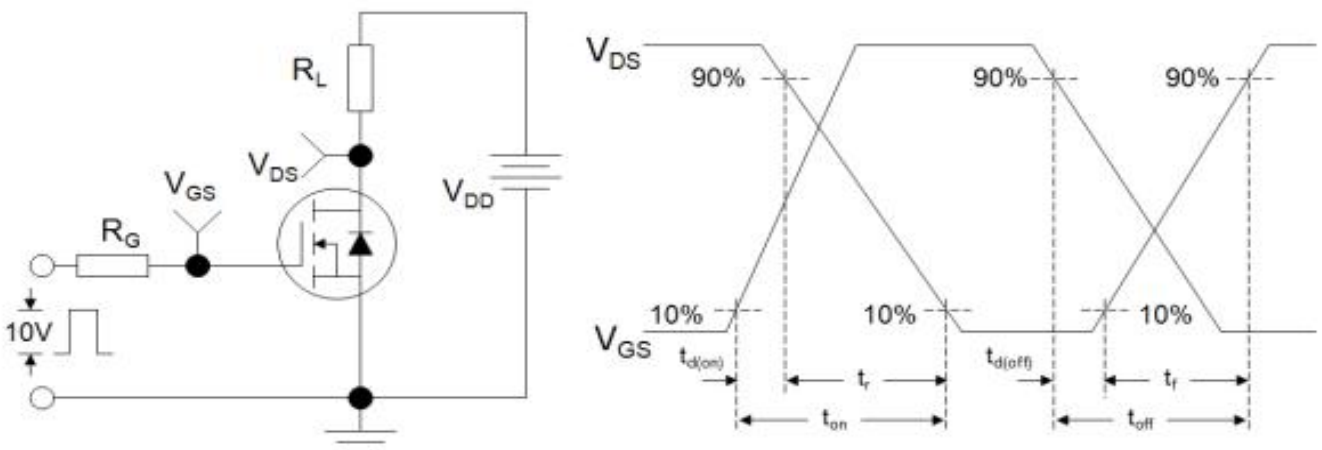


**Test Circuits and Waveforms**

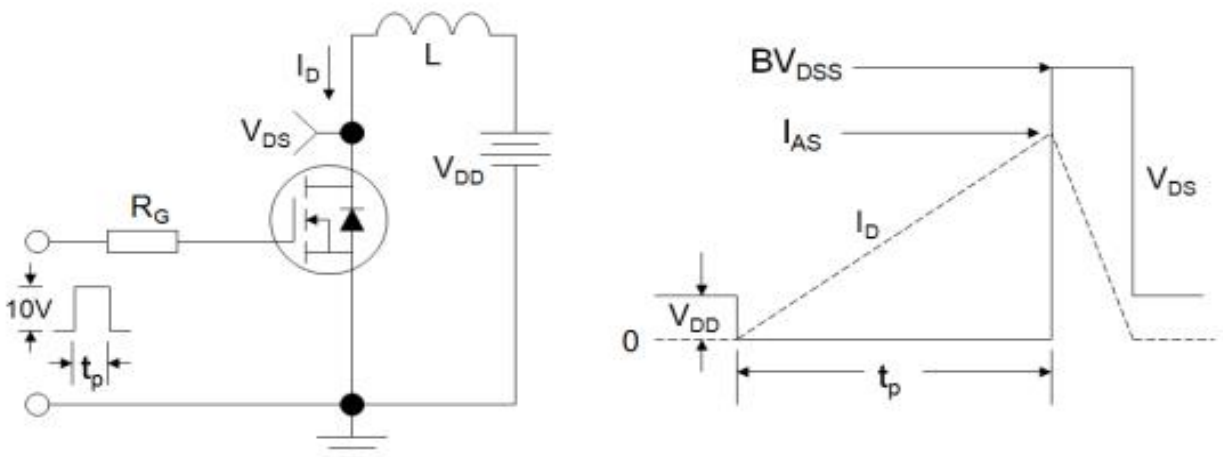
**Figure A: Gate Charge Test Circuit and Waveform**



**Figure B: Resistive Switching Test Circuit and Waveform**

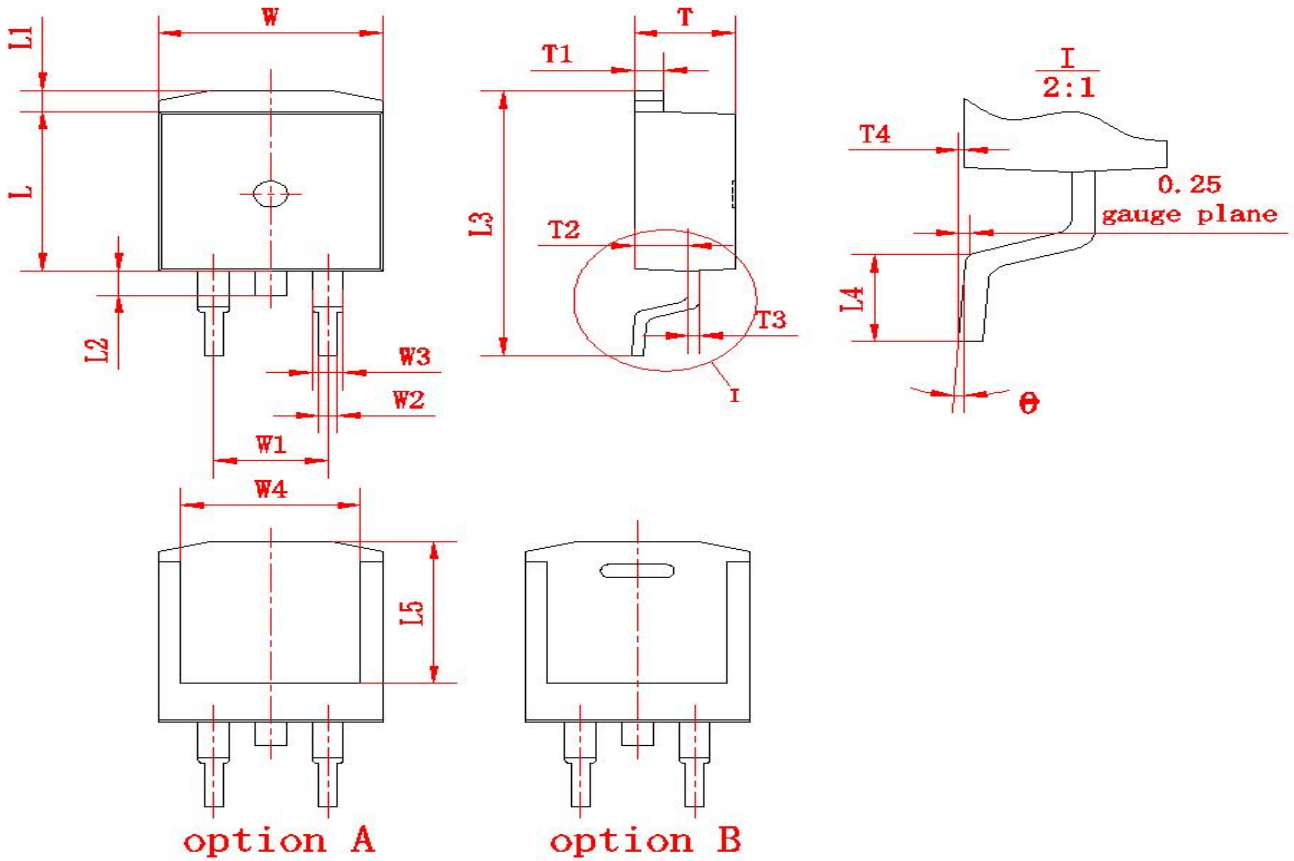


**Figure C: Unclamped Inductive Switching Test Circuit and Waveform**





Package outline drawing(TO-263 Unit: mm)



(单位: mm)

符号	尺寸		符号	尺寸		符号	尺寸	
	Min	Max		Min	Max		Min	Max
W	9.80	10.20	L1	1.00	1.40	T1	1.20	1.40
W1	(5.08)		L2	1.20	1.60	T2	2.20	2.60
W2	0.70	0.95	L3	15.00	15.60	T3	0.45	0.65
W3	1.17	1.62	L4	2.20	2.80	T4	0	0.25
W4	(8.0)		L5	(8.2)		$\theta$	0°	8°
L	9.00	9.40	T	4.30	4.70			

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